

## TAD 2.0 - THERMAL ADHESIVE

Data Sheet DS\_118 1/1



## DESCRIPTION

Thermal adhesive offers several advantages, including excellent thermal conductivity, high strength bonding, and resistance to high temperatures and environmental stress. It provides a reliable and permanent solution for attaching heat sinks, electronic components, and other materials requiring thermal management.

Thermal adhesive is easy to apply, allowing for precise positioning and customization. It is also environmentally friendly and has a long lifespan, making it a sustainable choice for various industries. Additionally, thermal adhesive can be formulated to cure quickly, reducing production time and increasing efficiency.



RoHS 3 / REACH  
Last updated compliance directive



## PART NUMBER:

Type	Sides	Resin	Conductivity	Shore	Thickness
XXX	X	X	XX 30	XXX	XXXX
			Thermal conductivity equal to 3 W/mK		

## TYPICAL APPLICATIONS:

- LED lighting
- Cooling chassis component
- Rack or other type of heat dissipation
- Heat pipe assembly
- Motor control
- Telecom hardware

Properties	UNITS	TAD1S200300	TEST METHOD
Color	-	Grey	Visual
Main ingredient	-	Silicone resin	***
Exterior	-	Semi-flow	***
Dry time	min	5/10	***
Curing conditions	h	24	***
Density	g/cm <sup>3</sup>	2,20/2,30	ASTM D297
Hardness	Shore A	40/60	ASTM D2240
Bond strength	Mpa	≥1,5	***
Temperature range	°C	-50/200	***
Breakdown voltage	KV/mm	20	ASTM D149
Volume resistivity	Ω·cm	3,0*10 <sup>13</sup>	ASTM D257
Thermal conductivity	W/mk	2,0	ASTM D5470
RoHS (10)	-	PASS	IEC 62321
Halogen (4)	-	PASS	EN14582
REACH (191)	-	PASS	EN14372

## STORAGE CONDITIONS

Store in a ventilated, cool and dry place, do not touch open flames. This product is nontoxic and is stored and transported as non-dangerous goods.